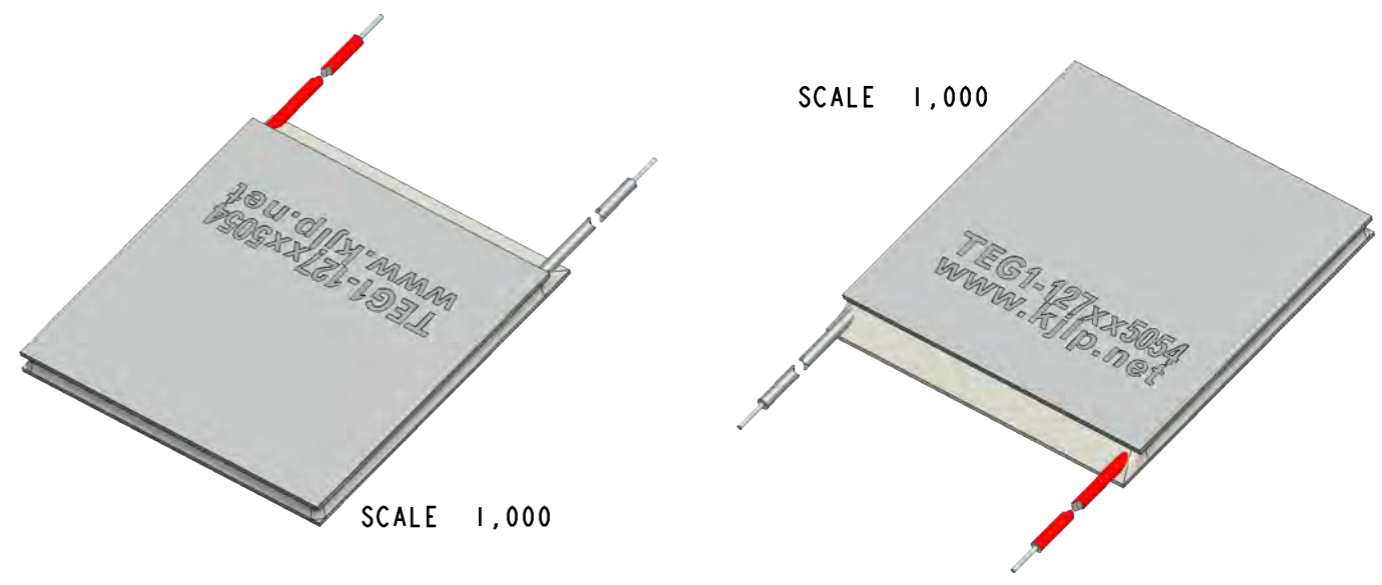
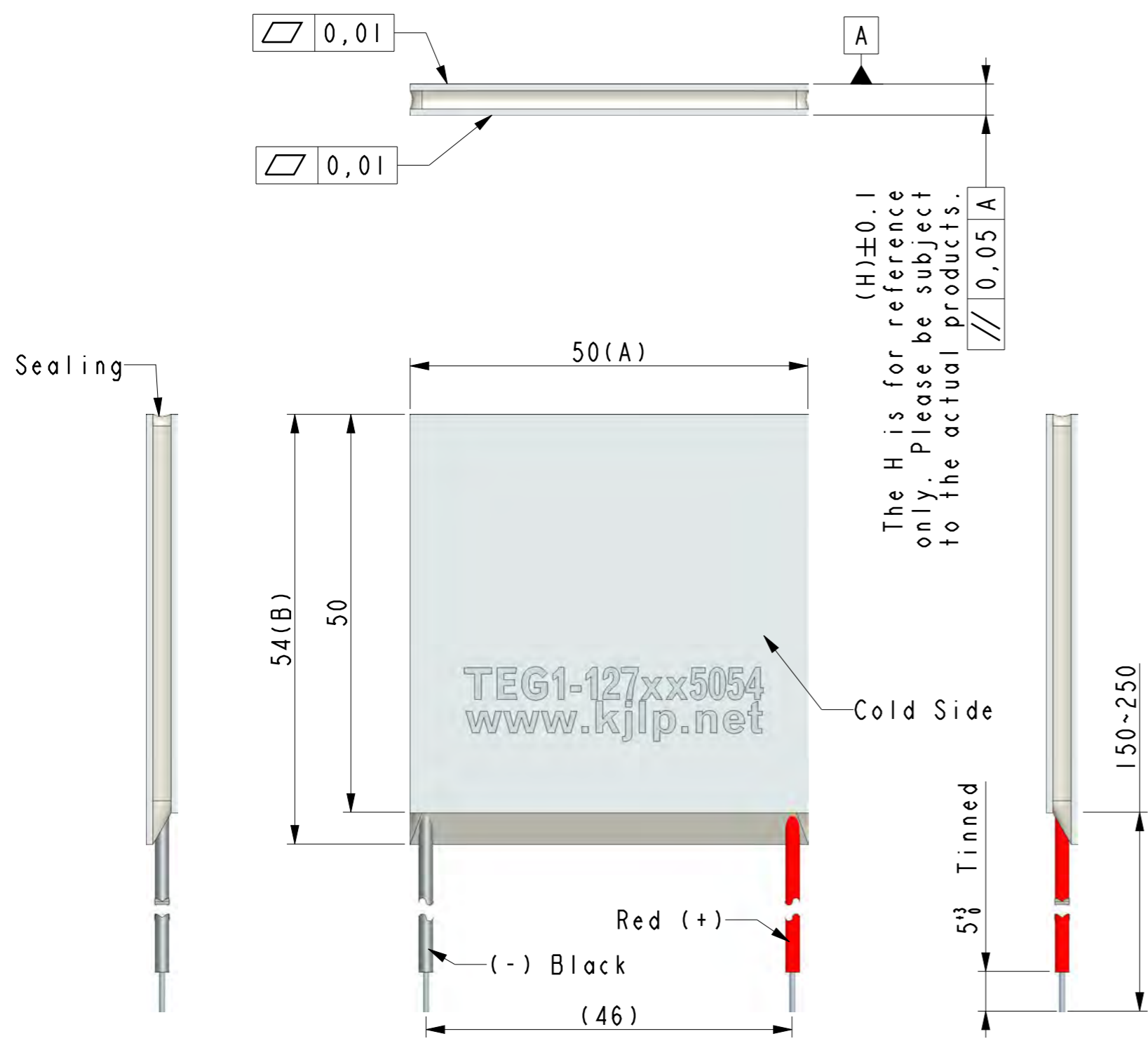


REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECR#
A		INITIAL CREATION	2013/01/01	Gary	Mason	



Part Number And Feature:

T	E	G	I	-	1	2	7	x	x	5	0	5	4	Sealing	YES
↓	↓				↓			↓		↓		↓		Operation Temperatur(Max.)	200°C(Max.)
Thermo	Electric	Chip	Stage		N & P	Stack	Quantity	R	Load	Dimension	(A)	Dimension	(B)	Melting Point	235°C
														Storage Temperature	-60°C~100°C
														RoHS	YES

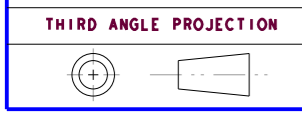
Technical Data:

ITEM	Part NO.	Stack(P&N)	U Load(Max.)	P Load(Max.)	R Load(Max.)	Uoc	P/N Size	DIM(A)	DIM(B)	DIM(H)
1	TEG1-127135054	127	3.4 V	8.9 W	1.3 Ohm	6.4 V	1.3*2.0*2.0	50	54	RF3.6
2	TEG1-127165054	127	3.4 V	7.4 W	1.6 Ohm	6.4 V	1.6*2.0*2.0	50	54	RF3.8

Notes:

1. Printing always on cold side.
2. Tolerance of thermo and electric parameters ±10%.
3. Please mount heat sink before you use it. also, please do not exceed the extra voltage at any time.

\*DO NOT SCALE DRAWING



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USED OR DISCLOSED OR IN PART TO ANYONE WITHOUT THE PERMISSION OF KJLP (SHENZHEN) ELECTRONICS  
CO., LTD.

1. UNLESS OTHERWISE SPECIFIED,  
DIMENSIONS ARE MM  
2 TOLERANCE ARE AS FOLLOWS:  
0 < X < 2 ± 0.06  
2 < X < 10 ± 0.08  
10 < X < 50 ± 0.12  
50 < X < 100 ± 0.16  
100 < X < 200 ± 0.20  
200 < X < 300 ± 0.30  
ANGLES ± 0.5°

PART NO.	TEG1-127xx5054		DESCRIPTION	127 P&N, 8.9~7.4W(Max.), 50*54mm			
	SIGNATURE	DATE		昆晶冷片(深圳)电子有限公司			
DRAWN BY	Gary	2013/01/01	 www.kjlp.net	KJLP (SHENZHEN) ELECTRONICS CO., LTD			
CHECKED BY	Justin	2013/01/01		email: kjlp@kjlp.net http:// www.kjlp.net			
ENGR	Vivi	2013/01/01		Tel: +86-755-82528352 Fax: +86-755-22639899			
APPROVED BY	Mason	2013/01/01		CAD MODLE:	TEG1-127xx5054.prt	SCALE: 1:1	REV: A
MATERIAL:	ISSUED BY	Jack	2013/01/01	CAD DWG:	TEG1-127xx5054.drw	SIZE: A3	SHEET: 1 OF 1